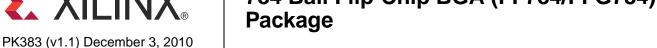
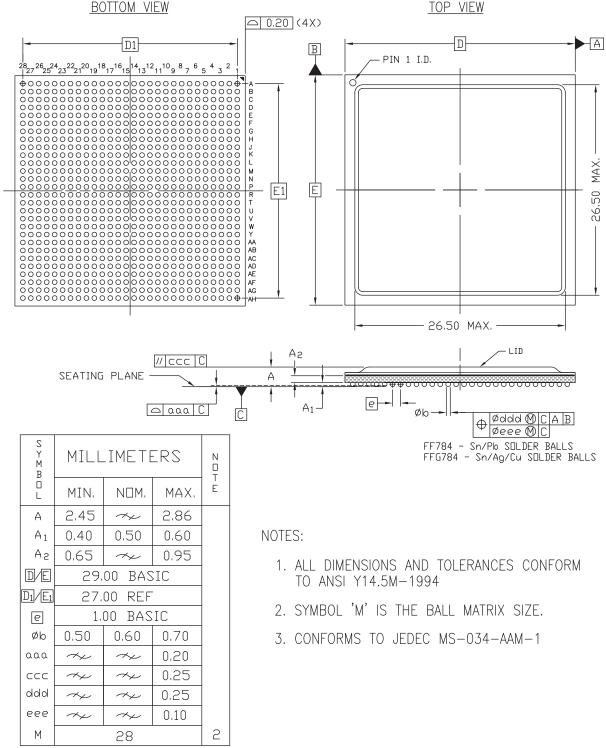


784 Ball Flip-Chip BGA (FF784/FFG784)





PK383_01_102210

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.
12/3/10	1.1	Changed maximum overall package thickness (symbol A) from 3.10 to 2.86.

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